


Date: 4/25/2021

Material Number: EFR32FG14P233F256GM48-B

Pkg Config.: PK1591

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	58.80	Carbon Black	1333-86-4	0.400	0.235	4000	0.1730	1730
			Epoxy Resin (Proprietary)	Proprietary	7.000	4.116	70000	3.0275	30275
			Metal Hydroxide	Proprietary	2.000	1.176	20000	0.8650	8650
			Phenol Resin (Proprietary)	Proprietary	5.000	2.940	50000	2.1625	21625
			Silica (Amorphous) B	60676-86-0	85.600	50.333	856000	37.0219	370219
2	Plating - External	4.20	Tin	7440-31-5	100.000	4.200	1000000	3.0893	30893
3	Bond Wire	0.35	Copper	7440-50-8	96.550	0.334	965500	0.2457	2457
			Gold	7440-57-5	0.350	0.001	3500	0.0009	9
			Palladium	7440-05-3	3.100	0.011	31000	0.0079	79
4	Die Attach Epoxy	1.90	Copper	7440-50-8	10.000	0.190	100000	0.1398	1398
			Hardener (Proprietary)	Proprietary	2.000	0.038	20000	0.0280	280
			Liquid Rubber	Proprietary	12.500	0.238	125000	0.1747	1747
			Mixed Diluents	Proprietary	6.500	0.124	65000	0.0908	908
			Modified Epoxy Resins	Proprietary	1.500	0.028	15000	0.0210	210
			Silver	7440-22-4	67.500	1.282	675000	0.9433	9433
5	Leadframe	65.30	Chromium	7440-47-3	0.270	0.176	2700	0.1297	1297
			Copper	7440-50-8	98.850	64.549	988500	47.4786	474786
			Silver	7440-22-4	0.430	0.281	4300	0.2065	2065
			Tin	7440-31-5	0.250	0.163	2500	0.1201	1201
			Zinc	7440-66-6	0.200	0.131	2000	0.0961	961
6	Plating - Internal	1.30	Silver	7440-22-4	100.000	1.300	1000000	0.9562	9562
7	Die	4.11	Silicon	7440-21-3	99.800	4.100	998000	3.0156	30156
			Silicon Dioxide	60676-86-0	0.200	0.008	2000	0.0060	60
	Total Unit Weight =	135.96				135.96		100.0000	1000000